9-Bit TTL to ECL Translator

Description

The MC10H/100H600 is a 9-bit, dual supply TTL to ECL translator. Devices in the ON Semiconductor 9-bit translator series utilize the PLCC-28 for optimal power pinning, signal flow-through and electrical performance.

The H600 features both ECL and TTL logic enable controls for maximum flexibility.

The 10H version is compatible with MECL 10H ECL logic levels. The 100H version is compatible with 100K levels.

Features

- 9-Bit Ideal for Byte-Parity Applications
- Flow-Through Configuration
- Extra TTL and ECL Power/Ground Pins to Minimize Switching Noise
- ECL and TTL Enable Inputs
- Dual Supply
- 3.5 ns Max D to Q
- PNP TTL Inputs for Low Loading
- Choice of ECL Compatibility: MECL 10H (10Hxxx) or 100K (100Hxxx)
- Pb-Free Packages are Available*



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PLCC-28 FN SUFFIX CASE 776

MARKING DIAGRAM*



xxx = 10 or 100

A = Assembly Location

WL = Wafer Lot YY = Year WW = Work Week G = Pb-Free Package

*For additional marking information, refer to Application Note AND8002/D.

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 4 of this data sheet.

^{*}For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

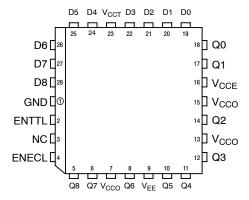


Figure 1. Pinout: PLCC-28 (Top View)

Table 1. PIN NAMES

PIN	FUNCTION
GND	TTL Ground (0 V)
V _{CCE}	ECL V _{CC} (0 V)
V _{CCO}	ECL V _{CC} (0 V) – Outputs
V _{CCT}	TTL Supply (+5.0 V)
V _{EE}	ECL Supply (-5.2/-4.5 V)
D0-D8	Data Inputs (TTL)
Q0-Q8	Data Outputs (ECL)
ENECL	Enable Control (ECL)
ENTTL	Enable Control (TTL)

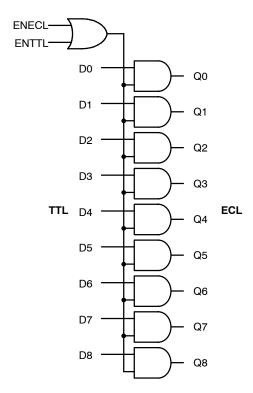


Figure 2. Logic Symbol

Table 2. TRUTH TABLE

ENECL	ENTTL	D	Q
Н	Х	Н	Н
Н	Χ	L	L
Х	Н	Н	Н
Х	Н	L	L
L	L	Х	L

Table 3. DC CHARACTERISTICS: $V_{CCT} = 5.0 \text{ V} \pm 10\%$; $V_{EE} = -5.2 \text{ V} \pm 5\%$ (10H version); $V_{EE} = -4.2 \text{ V}$ to -5.5 V (100H)

			0°	C.	25	°C	75	°C	
Symbol	Parameter		Min	Max	Min	Max	Min	Max	Unit
Power Supply Current									
I _{EE}	ECL	10H 100H		-125 -122		-125 -123		-125 -132	mA
I _{CCH} I _{CCL}	TTL			48 50		48 50		48 50	mA

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

Table 4. 10H ECL DC CHARACTERISTICS: V_{CCT} = 5.0 V ± 10%; V_{EE} = -5.2 V ± 5%

			0 °	Č.	25	°C	75	°C	
Symbol	Parameter	Condition	Min	Max	Min	Max	Min	Max	Unit
I _{INH}	Input HIGH Current Input LOW Current		0.5	225	0.5	175	0.5	175	μ Α μ Α
V _{IH} V _{IL}	Input HIGH Voltage Input LOW Voltage		-1170 -1950	-840 -1480	-1130 -1950	-810 -1480	-1070 -1950	-735 -1450	mV
V _{OH} V _{OL}	Output HIGH Voltage Output LOW Voltage	50 Ω to –2.0 V	-1020 -1950	-840 -1630	-980 -1950	-810 -1630	-920 -1950	-735 -1600	mV

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

Table 5. 100H ECL DC CHARACTERISTICS: $V_{CCT} = 5.0 \text{ V} \pm 10\%$; $V_{EE} = -4.2 \text{ V}$ to -5.5 V

			0 °	С	25	°C	75	°C	
Symbol	Parameter	Condition	Min	Max	Min	Max	Min	Max	Unit
I _{INH} I _{IL}	Input HIGH Current Input LOW Current		0.5	255	0.5	175	0.5	175	μ Α μ Α
V _{IH} V _{IL}	Input HIGH Voltage Input LOW Voltage		-1165 -1810	-880 -1475	-1165 -1810	-880 -1475	-1165 -1810	-880 -1475	mV
V _{OH} V _{OL}	Output HIGH Voltage Output LOW Voltage	50 Ω to -2.0 V	-1025 -1810	-880 -1620	-1025 -1810	-880 -1620	-1025 -1810	-880 -1620	mV

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

Table 6. TTL DC CHARACTERISTICS: V_{CCT} = 5.0 V ± 10%; V_{EE} = -5.2 V ± 5% (10H); V_{EE} = -4.2 V to -5.5 V (100H)

			0	°C	25	°C	75	°C	
Symbol	Parameter	Condition	Min	Max	Min	Max	Min	Max	Unit
V _{IH} V _{IL}	Input HIGH Voltage Input LOW Voltage		2.0	0.8	2.0	0.8	2.0	0.8	V V
I _{IH}	Input HIGH Current	V _{IN} = 2.7 V V _{IN} = 7.0 V		20 100		20 100		20 100	μА
I _{IL}	Input LOW Current	V _{IN} = 0.5 V		-0.6		-0.6		-0.6	mA
V _{IK}	Input Clamp Voltage	I _{IN} = −18 mA		-1.2		-1.2		-1.2	V

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

Table 7. AC CHARACTERISTICS: V_{CCT} = 5.0 V ± 10%; V_{EE} = -5.2 V ± 5% (10H); V_{EE} = -4.2 V to -5.5 V (100H)

				0°	C	25	°C	75	°C	
Symbol	Parameter		Condition	Min	Max	Min	Max	Min	Max	Unit
t _{PLH}	Propagation Delay to Output	D	50 Ω to –2.0 V	1.4	3.0	1.5	3.2	1.7	3.5	ns
t _{PHL}		ENECL/ ENTTL		1.8	3.7	1.9	3.9	2.0	4.1	ns
t _R t _F	Output Rise/Fall Time 20% – 80%)		0.5	1.5	0.5	1.5	0.5	1.5	ns

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

ORDERING INFORMATION

Device	Package	Shipping [†]
MC10H600FN	PLCC-28	37 Units / Rail
MC10H600FNG	PLCC-28 (Pb-Free)	37 Units / Rail
MC10H600FNR2	PLCC-28	500 / Tape & Reel
MC10H600FNR2G	PLCC-28 (Pb-Free)	500 / Tape & Reel
MC100H600FN	PLCC-28	37 Units / Rail
MC100H600FNG	PLCC-28 (Pb-Free)	37 Units / Rail
MC100H600FNR2	PLCC-28	500 / Tape & Reel
MC100H600FNR2G	PLCC-28 (Pb-Free)	500 / Tape & Reel

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

Resource Reference of Application Notes

AN1405/D - ECL Clock Distribution Techniques

AN1406/D - Designing with PECL (ECL at +5.0 V)

AN1503/D - ECLinPS™ I/O SPiCE Modeling Kit

AN1504/D - Metastability and the ECLinPS Family

AN1568/D - Interfacing Between LVDS and ECL

AN1672/D - The ECL Translator Guide

AND8001/D - Odd Number Counters Design

AND8002/D - Marking and Date Codes

AND8020/D - Termination of ECL Logic Devices

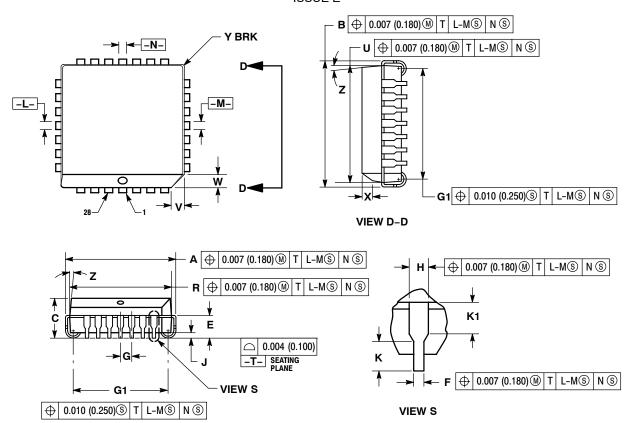
AND8066/D - Interfacing with ECLinPS

AND8090/D - AC Characteristics of ECL Devices

PACKAGE DIMENSIONS

PLCC-28 **FN SUFFIX**

PLASTIC PLCC PACKAGE CASE 776-02 ISSUE E



- DATUMS -L-, -M-, AND -N- DETERMINED
 WHERE TOP OF LEAD SHOULDER EXITS
- PLASTIC BODY AT MOLD PARTING LINE.

 2. DIMENSION G1, TRUE POSITION TO BE MEASURED AT DATUM -T-, SEATING PLANE.

 3. DIMENSIONS R AND U DO NOT INCLUDE MOLD FLASH. ALLOWABLE MOLD FLASH IS 0.010 (0.250) PER SIDE.
- 0.010 (0.250) PER SIDE.
 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 5. CONTROLLING DIMENSION: INCH.
 6. THE PACKAGE TOP MAY BE SMALLER THAN THE PACKAGE BOTTOM BY UP TO 0.012 (0.300). DIMENSIONS R AND U ARE DETERMINED AT THE OUTERMOST EXTREMES OF THE PLASTIC BODY EXCLUSIVE OF MOLD FLASH, TIE BAR BUIRDS, GATE BUIRDS, AND INTERLIFAD. BURRS, GATE BURRS AND INTERLEAD FLASH, BUT INCLUDING ANY MISMATCH BETWEEN THE TOP AND BOTTOM OF THE PLASTIC BODY.
- 7. DIMENSION H DOES NOT INCLUDE DAMBAR PROTRUSION OR INTRUSION. THE DAMBAR PROTRUSION(S) SHALL NOT CAUSE THE H DIMENSION TO BE GREATER THAN 0.037 (0.940). THE DAMBAR INTRUSION(S) SHALL NOT CAUSE THE H DIMENSION TO BE SMALLER THAN 0.025 (0.635).

	INC	HES	MILLIN	IETERS
DIM	MIN	MAX	MIN	MAX
Α	0.485	0.495	12.32	12.57
В	0.485	0.495	12.32	12.57
C	0.165	0.180	4.20	4.57
Е	0.090	0.110	2.29	2.79
F	0.013	0.019	0.33	0.48
G	0.050	BSC	1.27	BSC
Н	0.026	0.032	0.66	0.81
7	0.020		0.51	
K	0.025		0.64	
R	0.450	0.456	11.43	11.58
5	0.450	0.456	11.43	11.58
٧	0.042	0.048	1.07	1.21
W	0.042	0.048	1.07	1.21
Х	0.042	0.056	1.07	1.42
Υ		0.020		0.50
Z	2 °	10°	2°	10°
G1	0.410	0.430	10.42	10.92
K1	0.040		1.02	

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